


MATERIAL DECLARATION SHEET



Package Type	TCS-DL004-250-WH			
Product Line	Semiconductor Products			
Compliance Date	1 June 2012			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	0.014456	Fused Silica	60676-86-0	87.70	49.91	56.92
				Epoxy resin	Trade secret	5.00	2.85	
				Epoxy CN	29690-82-2	2.00	1.14	
				Phenol resin	Trade secret	5.00	2.85	
				Carbon Black	1333-86-4	0.30	0.17	
2	Leadframe	Copper alloy	0.008790	Copper	7440-50-8	93.32	32.29	34.60
				Iron	7439-89-6	2.20	0.76	
				Zinc	7440-66-6	0.01	0.00	
				Phosphorous	7723-14-0	0.03	0.01	
				Silver (Plating)	7440-22-4	4.45	1.54	
3	Chip	Silicon	0.001692	Silicon	7440-21-3	99.43	6.65	6.66
				Aluminum	7429-90-5	0.57	0.01	
4	Die Attach	Silver epoxy	0.000066	Silver	7440-22-4	75.00	0.19	0.26
				Epoxy	9003-36-5	25.00	0.06	
5	Bond wires	Gold	0.000050	Gold	7440-57-5	100.00	0.20	0.20
6	Terminal Finish	Matte Tin	0.000345	Matte Tin	7440-31-5	100.00	1.36	1.36
		Total Weight	0.0254000					

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.